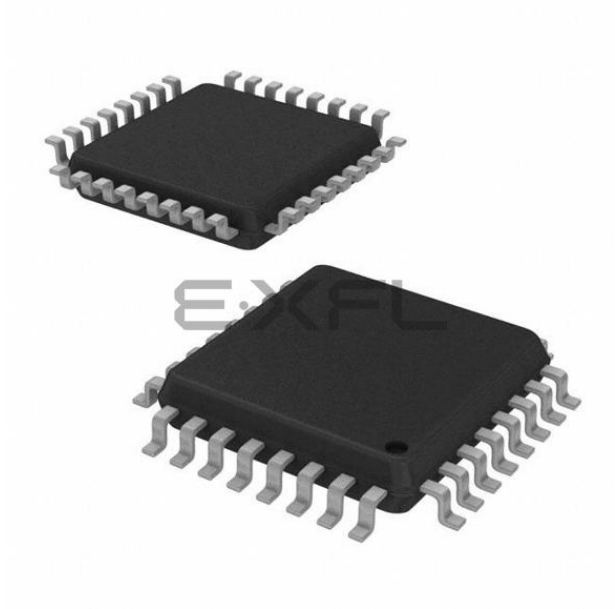

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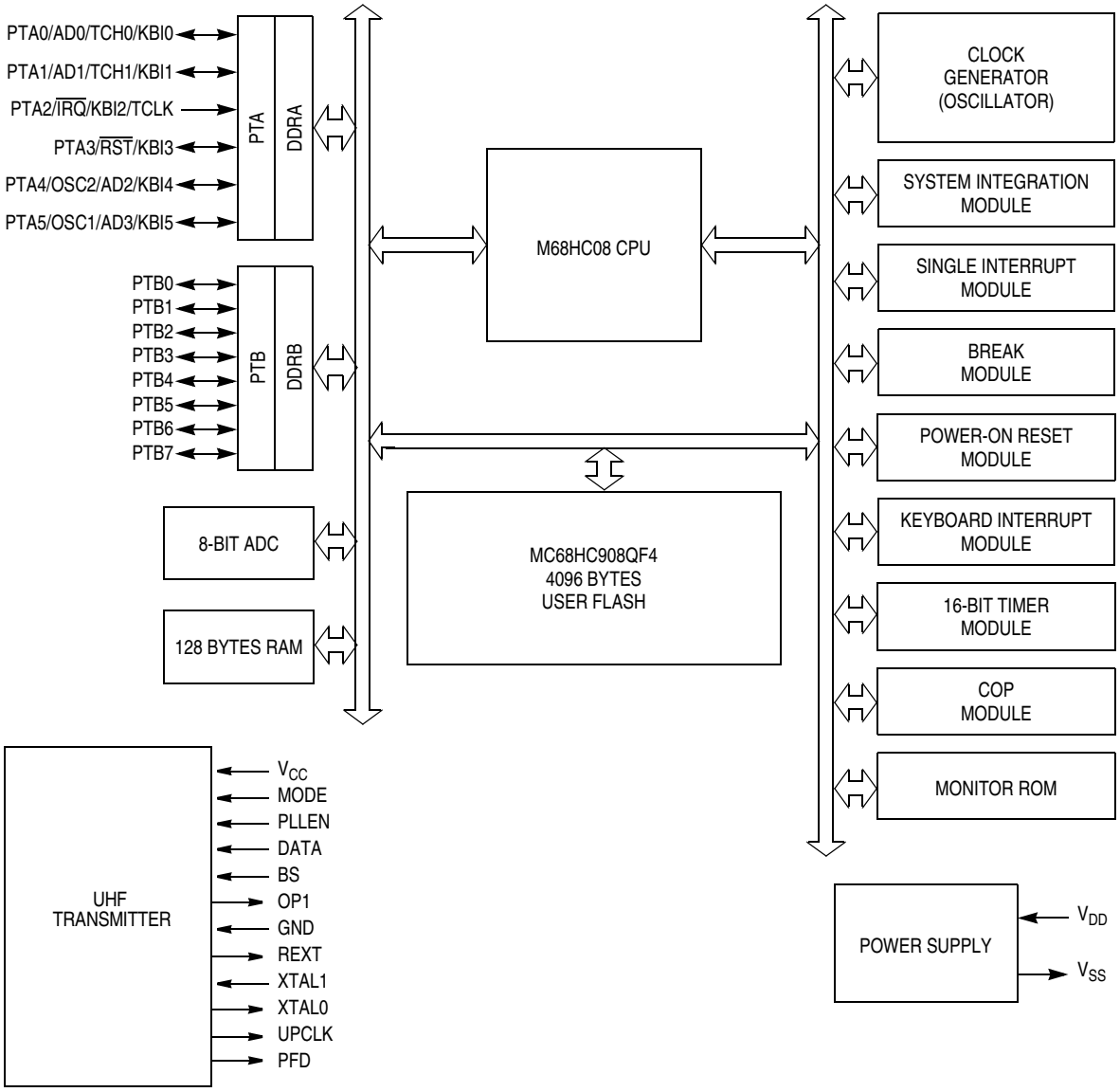
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	2MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc908qf4fj

Section 15. Timer Interface Module (TIM)



RST, IRQ: Pins have internal (about 30K Ohms) pull up
PTA[0:5]: High current sink and source capability
PTA[0:5]: Pins have programmable keyboard interrupt and pull up

Figure 1-1. Block Diagram

1.4 Pin Assignments

The MC68HC908QF4 is available in a 32-pin plastic low-profile quad flat pack (LQFP). **Figure 1-2** shows the pin assignment for this package.

Section 2. Memory

2.1 Introduction

The central processor unit (CPU08) can address 64 Kbytes of memory space. The memory map, shown in **Figure 2-1**, includes:

- 4096 bytes of user FLASH
- 128 bytes of random access memory (RAM)
- 48 bytes of user-defined vectors, located in FLASH
- 416 bytes of monitor read-only memory (ROM)
- 1536 bytes of FLASH program and erase routines, located in ROM

2.2 Unimplemented Memory Locations

Accessing an unimplemented location can have unpredictable effects on MCU operation. In **Figure 2-1** and in register figures in this document, unimplemented locations are shaded.

2.3 Reserved Memory Locations

Accessing a reserved location can have unpredictable effects on MCU operation. In **Figure 2-1** and in register figures in this document, reserved locations are marked with the word Reserved or with the letter R.

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$001D	IRQ Status and Control Register (INTSCR) See page 77.	Read:	0	0	0	0	IRQF1	0	IMASK1	MODE1
		Write:						ACK1		
		Reset:	0	0	0	0	0	0	0	0
$001E	Configuration Register 2 (CONFIG2)(1) See page 51.	Read:	IRQPUD	IRQEN	R	OSCOPT1	OSCOPT0	R	R	RSTEN
		Write:								
		Reset:	0	0	0	0	0	0	0	0(2)

1. One-time writable register after each reset.
2. RSTEN reset to 0 by a power-on reset (POR) only.

$001F	Configuration Register 1 (CONFIG1)(1) See page 52.	Read:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVDLVR	SSREC	STOP	COPD
		Write:								
		Reset:	0	0	0	0	0(2)	0	0	0

1. One-time writable register after each reset. Exceptions are LVDLVR and LVIRSTD bits.
2. LVDLVR reset to 0 by a power-on reset (POR) only.

$0020	TIM Status and Control Register (TSC) See page 147.	Read:	TOF	TOIE	TSTOP	0	0	PS2	PS1	PS0
		Write:	0			TRST				
		Reset:	0	0	1	0	0	0	0	0
$0021	TIM Counter Register High (TCNTH) See page 149.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$0022	TIM Counter Register Low (TCNTL) See page 149.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$0023	TIM Counter Modulo Register High (TMODH) See page 149.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	1	1	1	1	1	1	1	1
$0024	TIM Counter Modulo Register Low (TMODL) See page 149.	Read:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
		Write:								
		Reset:	1	1	1	1	1	1	1	1
$0025	TIM Channel 0 Status and Control Register (TSC0) See page 150.	Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
		Write:	0							
		Reset:	0	0	0	0	0	0	0	0
$0026	TIM Channel 0 Register High (TCH0H) See page 153.	Read:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
		Write:								
		Reset:	Indeterminate after reset							

= Unimplemented R = Reserved U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 2 of 5)

2.6 FLASH Memory (FLASH)

This subsection describes the operation of the embedded FLASH memory. The FLASH memory can be read, programmed, and erased from a single external supply. The program and erase operations are enabled through the use of an internal charge pump.

The FLASH memory consists of an array of 4096 bytes with an additional 48 bytes for user vectors. The minimum size of FLASH memory that can be erased is 64 bytes; and the maximum size of FLASH memory that can be programmed in a program cycle is 32 bytes (a row). Program and erase operations are facilitated through control bits in the FLASH control register (FLCR). Details for these operations appear later in this section. The address ranges for the user memory and vectors are:

- $EE00 – $FDFF; user memory, 4096 bytes
- $FFD0 – $FFFF; user interrupt vectors, 48 bytes.

NOTE: *An erased bit reads as 1 and a programmed bit reads as 0. A security feature prevents viewing of the FLASH contents.*[1]

2.6.1 FLASH Control Register

The FLASH control register (FLCR) controls FLASH program and erase operations.

Address: $FE08

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	HVEN	MASS	ERASE	PGM
Write:								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented

Figure 2-3. FLASH Control Register (FLCR)

HVEN — High Voltage Enable Bit

This read/write bit enables high voltage from the charge pump to the memory for either program or erase operation. It can only be set if either PGM =1 or ERASE =1 and the proper sequence for program or erase is followed.

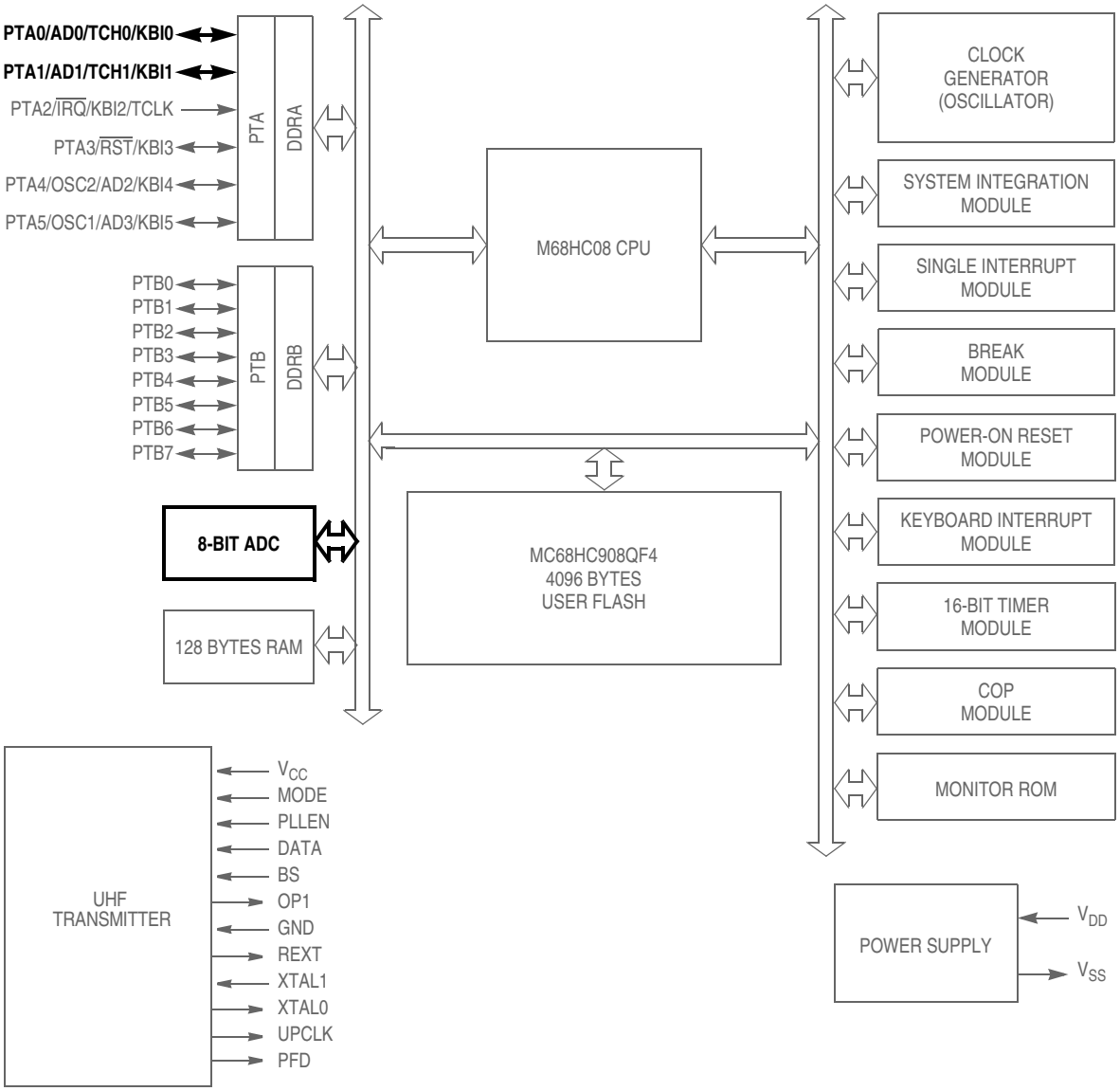
1 = High voltage enabled to array and charge pump on
0 = High voltage disabled to array and charge pump off

MASS — Mass Erase Control Bit

This read/write bit configures the memory for mass erase operation.

1 = Mass erase operation selected
0 = Mass erase operation unselected

1. No security feature is absolutely secure. However, Motorola's strategy is to make reading or copying the FLASH difficult for unauthorized users.



RST, IRQ: Pins have internal (about 30K Ohms) pull up
PTA[0:5]: High current sink and source capability
PTA[0:5]: Pins have programmable keyboard interrupt and pull up

Figure 3-2. Block Diagram Highlighting ADC Block and Pins

3.3.1 ADC Port I/O Pins

PTA0, PTA1, PTA4, and PTA5 are general-purpose I/O pins that are shared with the ADC channels. The channel select bits (ADC status and control register (ADSCR), $003C), define which ADC channel/port pin will be used as the input signal. The ADC overrides the port I/O logic by forcing that pin as input to the ADC. The remaining ADC channels/port pins are controlled by the port I/O logic and can be used as general-purpose I/O. Writes to the port register or data direction register (DDR) will not have any affect on the port pin that is selected by the ADC. Read of a port pin which is in use by the ADC will return a 0 if the corresponding DDR bit is at 0. If the DDR bit is 1, the value in the port data latch is read.

3.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD}, the ADC converts the signal to $FF (full scale). If the input voltage equals $V_{SS,}$ the ADC converts it to $00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in $FF if greater than V_{DD} and $00 if less than V_{SS}.

NOTE: *Input voltage should not exceed the analog supply voltages.*

3.3.3 Conversion Time

Sixteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1 MHz, then one conversion will take 16 μs to complete. With a 1-MHz ADC internal clock the maximum sample rate is 62.5 kHz.

$$\text{Conversion Time} = \frac{\text{16 ADC Clock Cycles}}{\text{ADC Clock Frequency}}$$

$$\text{Number of Bus Cycles} = \text{Conversion Time} \times \text{Bus Frequency}$$

3.3.4 Continuous Conversion

In the continuous conversion mode (ADCO = 1), the ADC continuously converts the selected channel filling the ADC data register (ADR) with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADSCR, $003C) is set after each conversion and will stay set until the next read of the ADC data register.

When a conversion is in process and the ADSCR is written, the current conversion data should be discarded to prevent an incorrect reading.

3.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

IRQPUD — $\overline{\text{IRQ}}$ Pin Pullup Control Bit
1 = Internal pullup is disconnected
0 = Internal pullup is connected between $\overline{\text{IRQ}}$ pin and V_{DD}

IRQEN — $\overline{\text{IRQ}}$ Pin Function Selection Bit
1 = Interrupt request function active in pin
0 = Interrupt request function inactive in pin

OSCOPT1 and OSCOPT0 — Selection Bits for Oscillator Option
(0, 0) Internal oscillator
(0, 1) External oscillator
(1, 0) External RC oscillator
(1, 1) External XTAL oscillator

RSTEN — $\overline{\text{RST}}$ Pin Function Selection
1 = Reset function active in pin
0 = Reset function inactive in pin

NOTE: *The RSTEN bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.*

Address: $001F

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVDLVR	SSREC	STOP	COPD
Reset:	0	0	0	0	U	0	0	0
POR:	0	0	0	0	0	0	0	0

U = Unaffected

Figure 5-2. Configuration Register 1 (CONFIG1)

COPRS (Out of STOP Mode) — COP Reset Period Selection Bit
1 = COP reset short cycle = $(2^{13} – 2^4) \times$ BUSCLKX4
0 = COP reset long cycle = $(2^{18} – 2^4) \times$ BUSCLKX4

COPRS (In STOP Mode) — Auto Wakeup Period Selection Bit
1 = Auto wakeup short cycle = $(2^9) \times$ INTRCOSC
0 = Auto wakeup long cycle = $(2^{14}) \times$ INTRCOSC

LVISTOP — LVI Enable in Stop Mode Bit
When the LVIPWRD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP.
1 = LVI enabled during stop mode
0 = LVI disabled during stop mode

9.3.2 Keyboard Initialization

When a keyboard interrupt pin is enabled, it takes time for the internal pullup to reach a logic 1. Therefore a false interrupt can occur as soon as the pin is enabled.

To prevent a false interrupt on keyboard initialization:

1. Mask keyboard interrupts by setting the IMASKK bit in the keyboard status and control register.
2. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.
3. Write to the ACKK bit in the keyboard status and control register to clear any false interrupts.
4. Clear the IMASKK bit.

An interrupt signal on an edge-triggered pin can be acknowledged immediately after enabling the pin. An interrupt signal on an edge- and level-triggered interrupt pin must be acknowledged after a delay that depends on the external load.

Another way to avoid a false interrupt:

1. Configure the keyboard pins as outputs by setting the appropriate DDRA bits in the data direction register A.
2. Write 1s to the appropriate port A data register bits.
3. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.

9.4 Wait Mode

The keyboard module remains active in wait mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of wait mode.

9.5 Stop Mode

The keyboard module remains active in stop mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of stop mode.

9.6 Keyboard Module During Break Interrupts

The system integration module (SIM) controls whether the keyboard interrupt latch can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state.

To allow software to clear the keyboard interrupt latch during a break interrupt, write a 1 to the BCFE bit. If a latch is cleared during the break state, it remains cleared when the MCU exits the break state.

The LVI is enabled out of reset. The LVI module contains a bandgap reference circuit and comparator. Clearing the LVI power disable bit (LVIPWRD) enables the LVI to monitor V_{DD} voltage. Clearing the LVI reset disable bit (LVIRSTD) enables the LVI module to generate a reset when V_{DD} falls below a voltage, V_{TRIPF} or V_{DTRIPF}. Setting the LVI enable in stop mode bit (LVISTOP) enables the LVI to operate in stop mode. Setting the LVD or LVR trip point bit (LVDLVR) selects the LVD trip point voltage. The actual trip thresholds are specified in **17.5 DC Electrical Characteristics**. Either trip level can be used as a detect or reset.

NOTE: *After a power-on reset, the LVI's default mode of operation is LVR trip voltage. If a higher trip voltage is desired, the user must set the LVDLVR bit to raise the trip point to the LVD voltage.*

If the user requires the higher trip voltage and sets the LVDLVR bit after power-on reset while the VDD supply is not above the V_{TRIPR} for LVD mode, the microcontroller unit (MCU) will immediately go into reset. The next time the LVI releases the reset, the supply will be above the V_{TRIPR} for LVD mode.

Once an LVI reset occurs, the MCU remains in reset until V_{DD} rises above a voltage, V_{TRIPR}, which causes the MCU to exit reset. See **Section 14. System Integration Module (SIM)** for the reset recovery sequence.

The output of the comparator controls the state of the LVIOUT flag in the LVI status register (LVISR) and can be used for polling LVI operation when the LVI reset is disabled.

10.3.1 Polled LVI Operation

In applications that can operate at V_{DD} levels below the V_{TRIPF} level, software can monitor V_{DD} by polling the LVIOUT bit. In the configuration register, the LVIPWRD bit must be cleared to enable the LVI module, and the LVIRSTD bit must be set to disable LVI resets.

10.3.2 Forced Reset Operation

In applications that require V_{DD} to remain above the V_{TRIPF} level, enabling LVI resets allows the LVI module to reset the MCU when V_{DD} falls below the V_{TRIPF} level. In the configuration register, the LVIPWRD and LVIRSTD bits must be cleared to enable the LVI module and to enable LVI resets.

10.3.3 Voltage Hysteresis Protection

Once the LVI has triggered (by having V_{DD} fall below V_{TRIPF}), the LVI will maintain a reset condition until V_{DD} rises above the rising trip point voltage, V_{TRIPR}. This prevents a condition in which the MCU is continually entering and exiting reset if V_{DD} is approximately equal to V_{TRIPF}. V_{TRIPR} is greater than V_{TRIPF} by the hysteresis voltage, V_{HYS}.

11.3.2 External Oscillator

The external clock option is designed for use when a clock signal is available in the application to provide a clock source to the microcontroller. The OSC1 pin is enabled as an input by the oscillator module. The clock signal is used directly to create BUSCLKX4 and also divided by two to create BUSCLKX2.

In this configuration, the OSC2 pin cannot output BUSCLKX4. So the OSC2EN bit in the port A pullup enable register will be clear to enable PTA4 I/O functions on the pin.

11.3.3 XTAL Oscillator

The XTAL oscillator circuit is designed for use with an external low-frequency crystal or ceramic resonator to provide an accurate clock source. In this configuration, the OSC2 pin is dedicated to the external crystal circuit. The OSC2EN bit in the port A pullup enable register has no effect when this clock mode is selected.

In its typical configuration, the XTAL oscillator is connected in a Pierce oscillator configuration, as shown in **Figure 11-2**. This figure shows only the logical representation of the internal components and may not represent actual circuitry. The oscillator configuration uses five components:

- Crystal, X_1
- Fixed capacitor, C_1
- Tuning capacitor, C_2 (can also be a fixed capacitor)
- Feedback resistor, R_B
- Series resistor, R_S

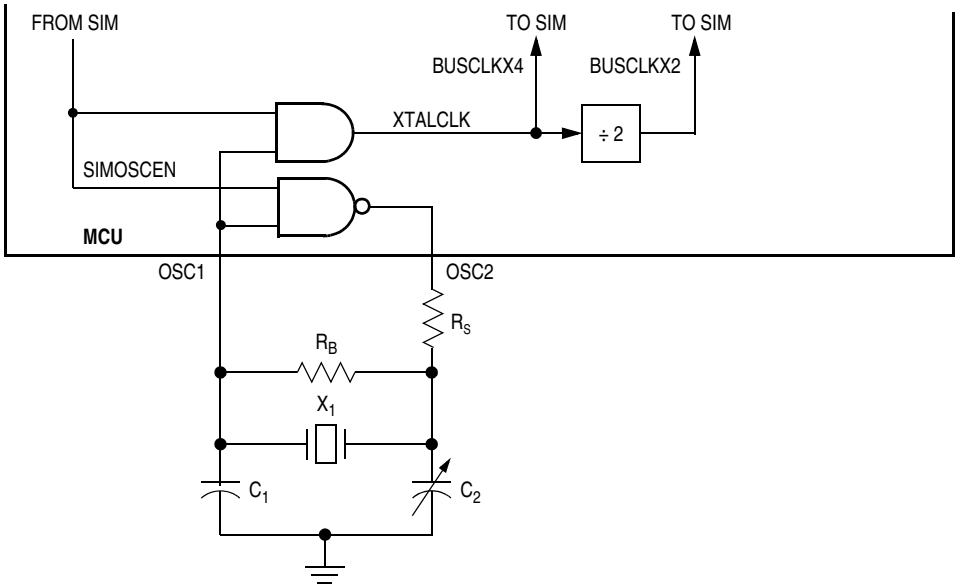


Figure 11-2. XTAL Oscillator External Connections

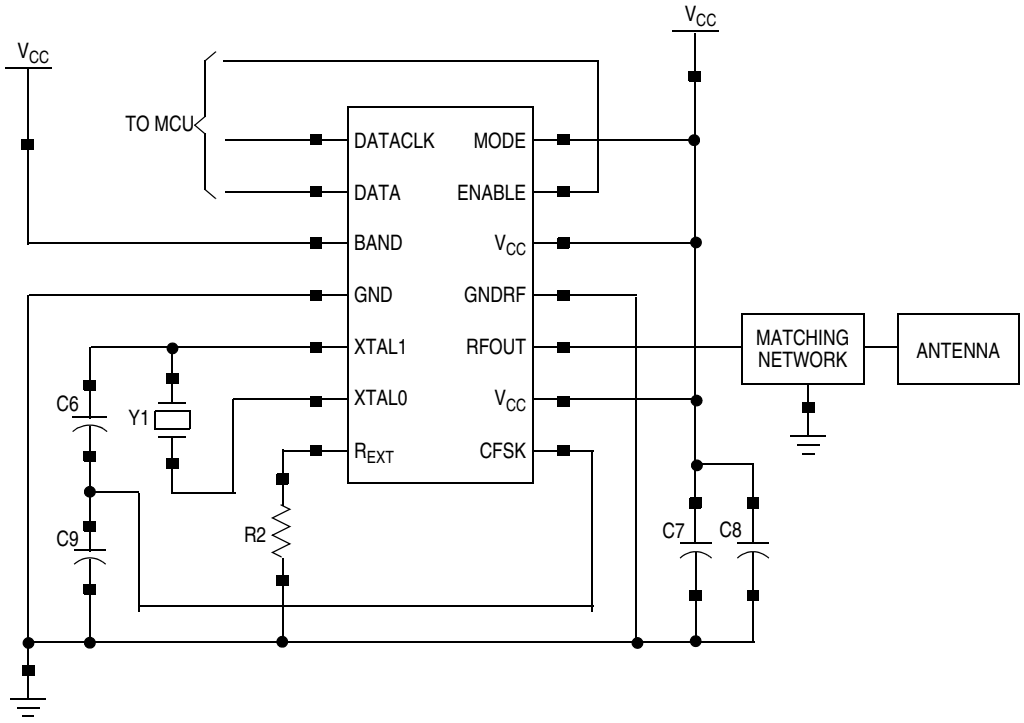


Figure 12-6. Application Schematic in FSK Modulation, 315-MHz and 434-MHz Frequency Bands

Table 12-3. Component Description

Component	Function	Value	Unit
Y1	Crystal	315-MHz band: 9.84, see **Table 12-5**	MHz
		434-MHz band: 13.56, see **Table 12-5**	MHz
		868-MHz band: 13.56, see **Table 12-5**	MHz
R2	RF output level setting resistor (R_{EXT})	12	kΩ
C6	Crystal load capacitor	OOK modulation: 18	pF
		FSK modulation: 22	pF
C7	Power supply decoupling capacitor	10	nF
C8		100	pF
C9	Crystal pulling capacitor for FSK modulation only	See **Table 12-5**	pF

14.6.2 Interrupt Status Registers

The flags in the interrupt status registers identify maskable interrupt sources. Table 14-3 summarizes the interrupt sources and the interrupt status register flags that they set. The interrupt status registers can be useful for debugging.

Table 14-3. Interrupt Sources

Priority	Source	Flag	Mask[1]	INT Register Flag	Vector Address
Highest	Reset	—	—	—	$FFFE–$FFFF
↕	SWI instruction	—	—	—	$FFFC–$FFFD
↕	$\overline{\text{IRQ}}$ pin	IRQF	IMASK	IF1	$FFFA–$FFFB
↕	Timer channel 0 interrupt	CH0F	CH0IE	IF3	$FFF6–$FFF7
↕	Timer channel 1 interrupt	CH1F	CH1IE	IF4	$FFF4–$FFF5
↕	Timer overflow interrupt	TOF	TOIE	IF5	$FFF2–$FFF3
↕	Keyboard interrupt	KEYF	IMASKK	IF14	$FFE0–$FFE1
Lowest	ADC conversion complete interrupt	COCO	AIEN	IF15	$FFDE–$FFDF

1. The I bit in the condition code register is a global mask for all interrupt sources except the SWI instruction.

14.6.2.1 Interrupt Status Register 1

Address: $FE04

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	IF5	IF4	IF3	0	IF1	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0

R = Reserved

Figure 14-12. Interrupt Status Register 1 (INT1)

IF1 and IF3–IF5 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 14-3.

1 = Interrupt request present

0 = No interrupt request present

Bit 0, 1, 3, and 7 — Always read 0

15.4.4.2 Buffered PWM Signal Generation

Channels 0 and 1 can be linked to form a buffered PWM channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the pulse width of the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The TIM channel 0 registers initially control the pulse width on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the pulse width at the beginning of the next PWM period. At each subsequent overflow, the TIM channel registers (0 or 1) that control the pulse width are the ones written to last. TSC0 controls and monitors the buffered PWM function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE: *In buffered PWM signal generation, do not write new pulse width values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered PWM signals.*

15.4.4.3 PWM Initialization

To ensure correct operation when generating unbuffered or buffered PWM signals, use the following initialization procedure:

1. In the TIM status and control register (TSC):
   a. Stop the TIM counter by setting the TIM stop bit, TSTOP.
   b. Reset the TIM counter and prescaler by setting the TIM reset bit, TRST.
2. In the TIM counter modulo registers (TMODH:TMODL), write the value for the required PWM period.
3. In the TIM channel x registers (TCHxH:TCHxL), write the value for the required pulse width.
4. In TIM channel x status and control register (TSCx):
   a. Write 0:1 (for unbuffered output compare or PWM signals) or 1:0 (for buffered output compare or PWM signals) to the mode select bits, MSxB:MSxA. See **Table 15-3**.
   b. Write 1 to the toggle-on-overflow bit, TOVx.
   c. Write 1:0 (polarity 1 — to clear output on compare) or 1:1 (polarity 0 — to set output on compare) to the edge/level select bits, ELSxB:ELSxA. The output action on compare must force the output to the complement of the pulse width level. See **Table 15-3**.

NOTE: *In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error*

or noise. Toggling on output compare can also cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.

5. In the TIM status control register (TSC), clear the TIM stop bit, TSTOP.

Setting MS0B links channels 0 and 1 and configures them for buffered PWM operation. The TIM channel 0 registers (TCH0H:TCH0L) initially control the buffered PWM output. TIM status control register 0 (TSCR0) controls and monitors the PWM signal from the linked channels. MS0B takes priority over MS0A.

Clearing the toggle-on-overflow bit, TOVx, inhibits output toggles on TIM overflows. Subsequent output compares try to force the output to a state it is already in and have no effect. The result is a 0% duty cycle output.

Setting the channel x maximum duty cycle bit (CHxMAX) and setting the TOVx bit generates a 100% duty cycle output. See **15.9.4 TIM Channel Status and Control Registers**.

15.5 Interrupts

The following TIM sources can generate interrupt requests:

- TIM overflow flag (TOF) — The TOF bit is set when the TIM counter reaches the modulo value programmed in the TIM counter modulo registers. The TIM overflow interrupt enable bit, TOIE, enables TIM overflow CPU interrupt requests. TOF and TOIE are in the TIM status and control register.
- TIM channel flags (CH1F:CH0F) — The CHxF bit is set when an input capture or output compare occurs on channel x. Channel x TIM CPU interrupt requests are controlled by the channel x interrupt enable bit, CHxIE. Channel x TIM CPU interrupt requests are enabled when CHxIE = 1. CHxF and CHxIE are in the TIM channel x status and control register.

15.6 Wait Mode

The WAIT instruction puts the MCU in low power-consumption standby mode.

The TIM remains active after the execution of a WAIT instruction. In wait mode the TIM registers are not accessible by the CPU. Any enabled CPU interrupt request from the TIM can bring the MCU out of wait mode.

If TIM functions are not required during wait mode, reduce power consumption by stopping the TIM before executing the WAIT instruction.

16.3.1.7 Commands

The monitor ROM firmware uses these commands:

- READ (read memory)
- WRITE (write memory)
- IREAD (indexed read)
- IWRITE (indexed write)
- READSP (read stack pointer)
- RUN (run user program)

The monitor ROM firmware echoes each received byte back to the PTA0 pin for error checking. An 11-bit delay at the end of each command allows the host to send a break character to cancel the command. A delay of two bit times occurs before each echo and before READ, IREAD, or READSP data is returned. The data returned by a read command appears after the echo of the last byte of the command.

NOTE: *Wait one bit time after each echo before sending the next byte.*

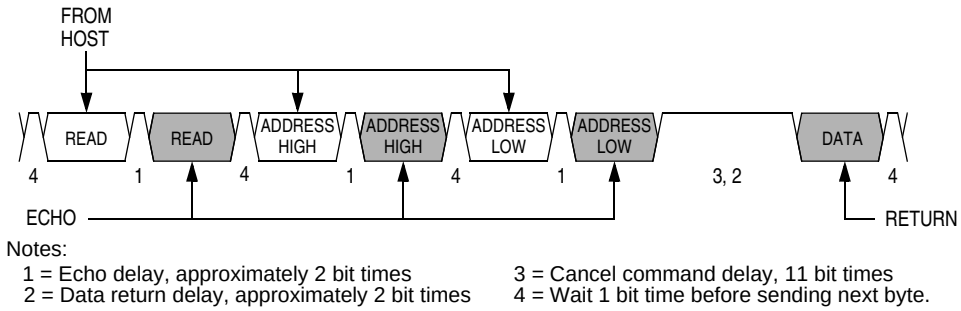


Figure 16-16. Read Transaction

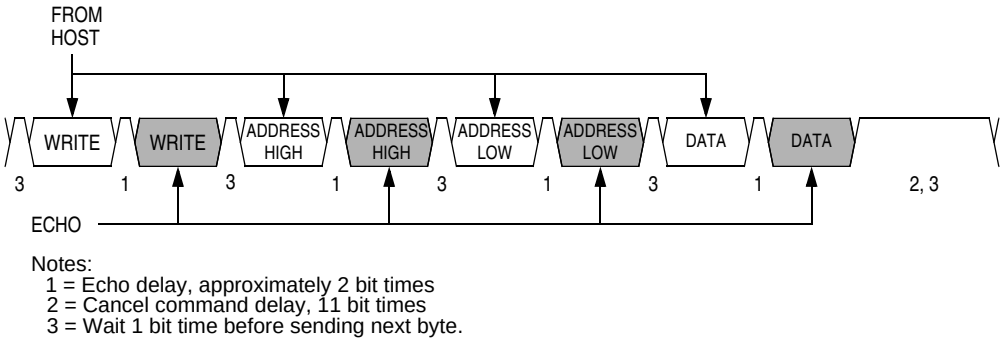


Figure 16-17. Write Transaction

A brief description of each monitor mode command is given in **Table 16-3** through **Table 16-8**.

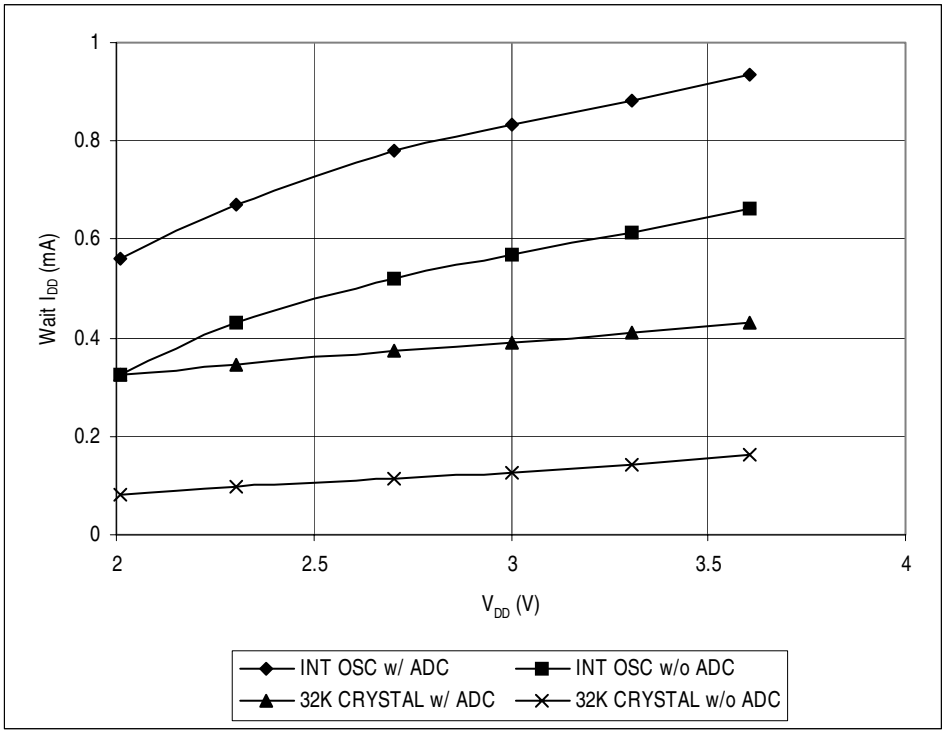


Figure 17-6. Typical Wait Current versus V_{DD} (25°C)
(f_{Bus} = 1 MHz for Internal Oscillator, f_{Bus} = 8 kHz for Crystal Oscillator)

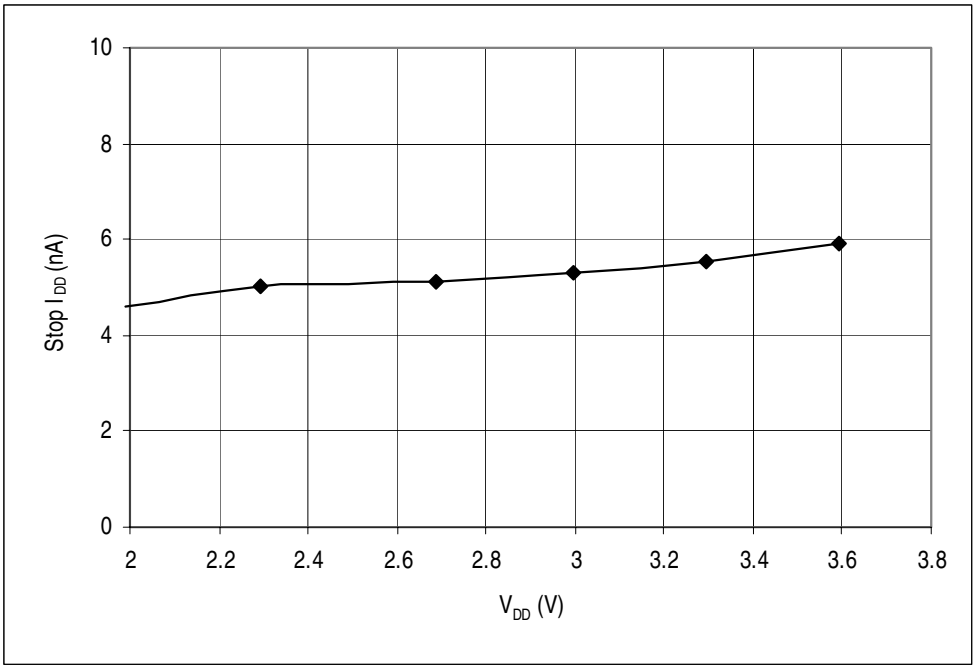


Figure 17-7. Typical Stop Current versus V_{DD} (25°C)

Section 18. Ordering Information and Mechanical Specifications

18.1 Introduction

This section provides ordering information and mechanical specifications for the 32-pin low-profile quad flat pack (LQFP).

The package outline given here reflects the latest package drawing at the time of publication. To make sure that you have the latest package specification, contact your local Motorola Sales Office.

18.2 MC Order Numbers

Table 18-1. Available MC Order Numbers

MC Order Number	Operating Temperature Range	Package
MC908QF4CFJ	–40°C to +85°C	32-pin LQFP
MC908QF4FJ	0°C to +70°C	32-pin LQFP

Temperature and package designators:
C = –40°C to +85°C
FJ = Low-profile quad flat pack (LQFP)

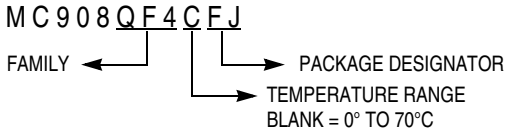


Figure 18-1. Device Numbering System